

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/604,164

Applicant(s): Gardecki et al.

Filed.: June 28, 2003

Art Unit: 2823

Dkt. No.: BUR920030026US1

Examiner: Brook Kcbede

Title: METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS

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Honorable Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

REQUEST FOR RECONSIDERATION

This Request for Reconsideration is being filed in response to the Office Action mailed on May 17, 2005. Applicants request this Amendment be entered in the above-identified application and reconsideration of the application in view of the Amendments and Remarks that follow.

BUR9-2003-0026-US1

6/7/2005

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